Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN170401 **Date:** March 14, 2017

Subject: Qualification of ChipMOS as an Additional Assembly Site for Select 54-Lead TSOP II Products

To: TOKYO ELECTRON DEVICE
TELDEVICE
cy-inside@teldevice.co.jp

Description of Change:
Cypress announces the qualification of ChipMOS Technologies Inc, Taiwan as an additional assembly site for select 54-Lead TSOP II (400mils) Pb-Free package products. The qualification of this facility will enable Cypress to tailor assembly operations to meet our customers' stringent quality and reliability requirements in our effort to continually provide world-class service.

54-Lead TSOP II (400mils) Pb-Free packages are assembled at ChipMOS Technologies using the following set of materials.

For Marketing Part Number: CY14B116M-xxxxxxxxx & CY14B116N-xxxxxxxxx:

Material	ChipMOS Set of Material	ASE-KH Taiwan Set of Material
Mold Compound	Hitachi 9200HF-U	EME-G631SH
Lead Frame	Alloy 42	Alloy 42
Die Attach Epoxy	Nitto EM710	FH900
Bond Wire	Gold	Cu / PdCu

For Marketing Part Number: CG8131AA, CY14B104x-xxxxxx, CY7C1061xxxx-xxxxxx, CY7C1069x-xxxxxx, CY7S1061xx-xxxxxx:

Material	ChipMOS Set of Material	ASE_KH Taiwan Set of Material
Mold Compound	9200HF-U	EME-G631SH
Lead Frame	Cu	Alloy 42
Die Attach Epoxy	EN4900	CRM1076
Bond Wire	Gold	Gold / Cu / PdCu

Benefit of Change:
Qualification of alternate manufacturing sites is part of Cypress's continuous improvement in our flexible manufacturing initiative providing Cypress with the added capability to meet upside market demand, reduce business continuity risk, and ensure consistent and reliable delivery to customers in dynamic, changing market conditions.

Affected Parts: 50

Part Numbers Affected: See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN will include all changes outlined in this PCN.

Qualification Status:

The changes listed in this PCN have been qualified through a series of tests documented in Qualification Test Plans (QTPs) 163002 and 163503. These qualification reports can be found as an attachments to this notification.

Sample Status:

Samples of the 54-Lead TSOP II part numbers are available as indicated in the attached 'Affected Parts List' file. Please contact your Sales Representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

Effective 90 days from the date of this notification or upon customer approval, whichever comes first, all shipments of the affected part numbers in the attached file may be sourced from ChipMOS Technologies Inc. Taiwan or from the other qualified manufacturing sites.

Anticipated Impact:

There is no anticipated impact associated with the transfer to product form, fit, function, performance, reliability, quality or product delivery.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration